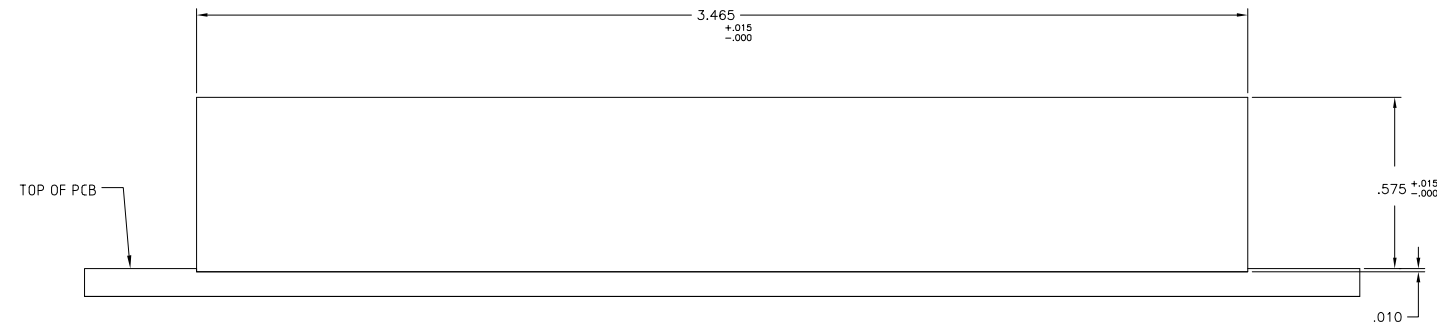
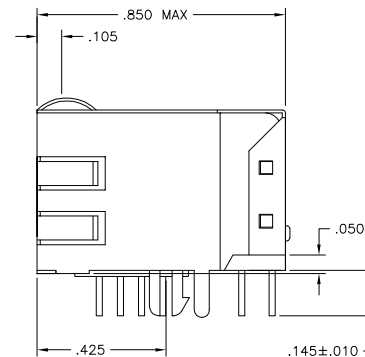
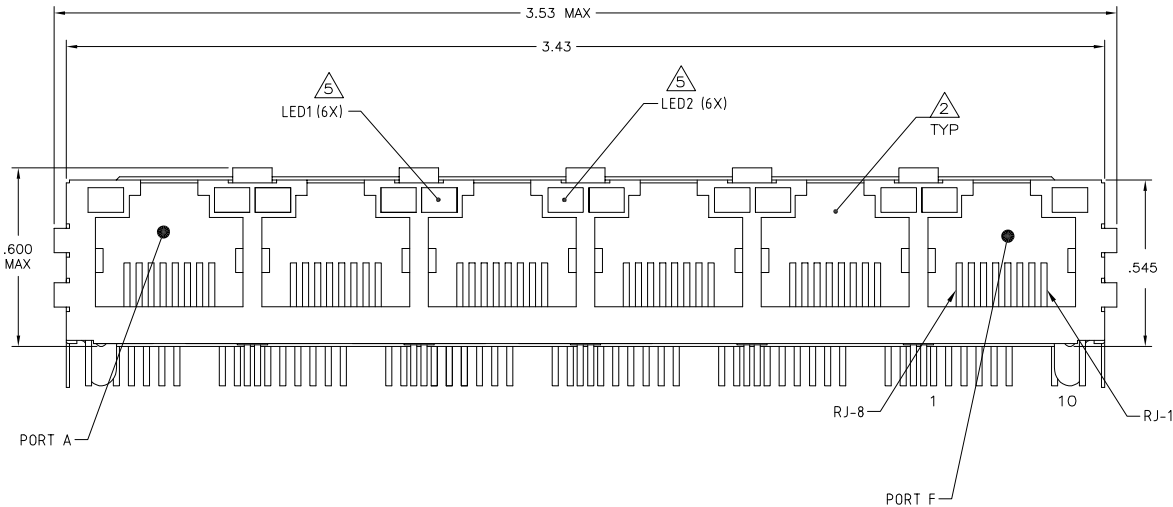
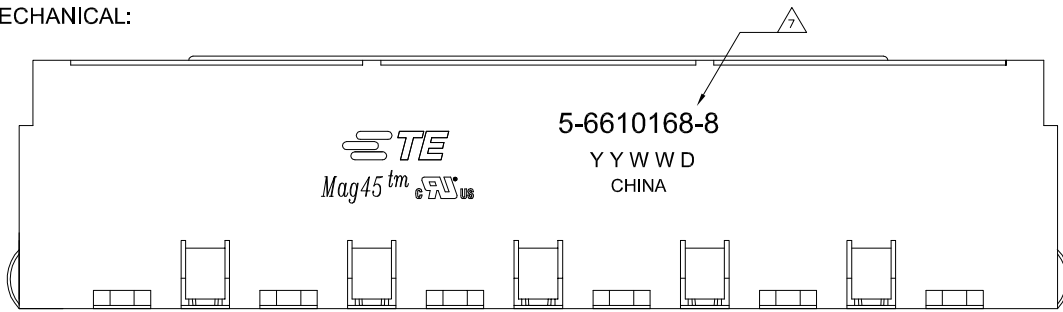


MECHANICAL:



1X6 SUGGESTED PANEL CUTOUT

LOC	QTY	REV	PER	DESCRIPTION	DATE	BY	APP'D
AA	22						
C				ECO-08-028138	19SEP2008	VL	TX
D				ECO-11-015772	30MAY2011	EL	LR

MATERIALS:
 -HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 -SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 -MOD JACK CONTACTS - 0.0157" X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 -LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.

RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

MAGNETICS
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, TX AND RX
 -POE CURRENT: 350mADC MAX
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE:1500VAC (MAX) AT 60Hz FOR 60 SECS WITH ALL PORTS CONNECTED.

4. OPERATING TEMPERATURE: FROM -40°C TO +85°C.

LEDS WITHOUT BUILT-IN RESISTOR
 LEADS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA
 LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20 mA

INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX.

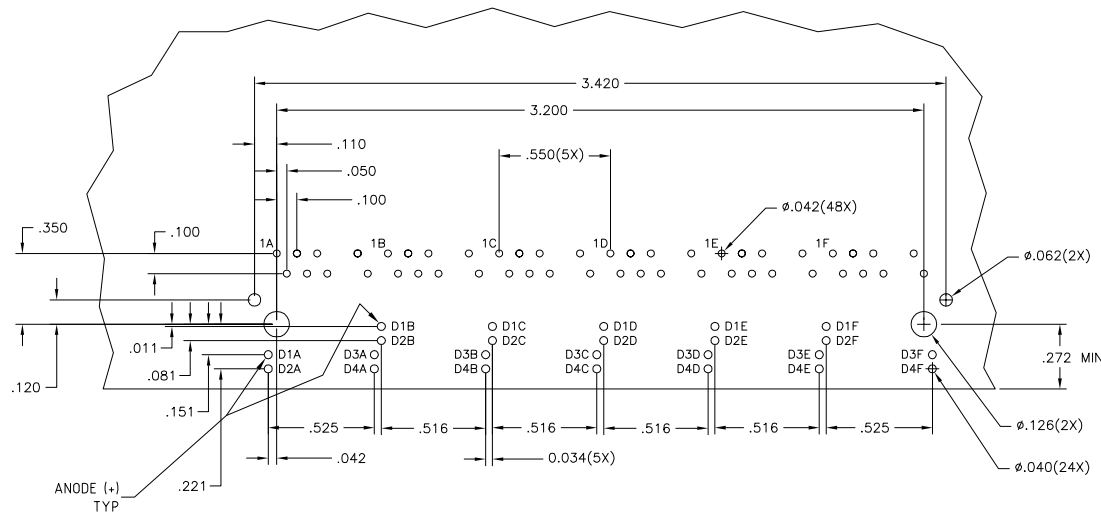
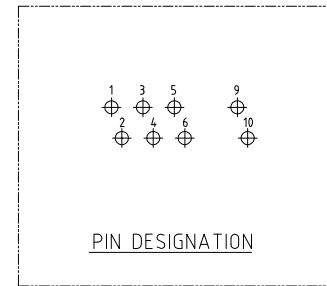
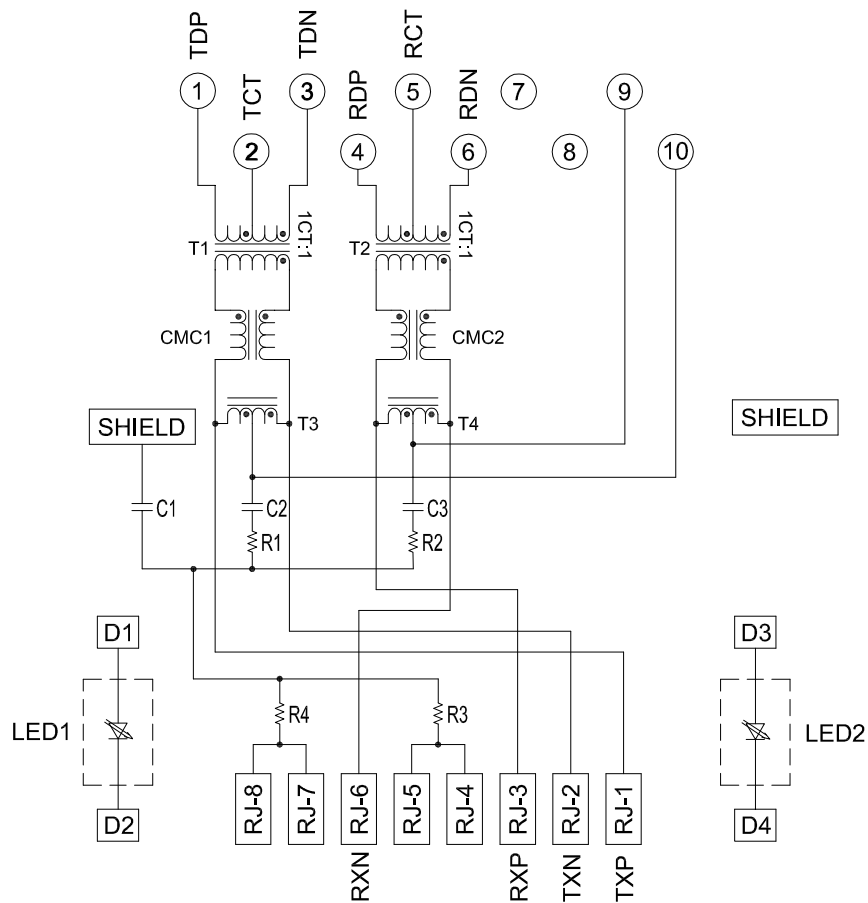
TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

GREEN	YELLOW	5-6610168-8
LED1	LED2	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY: ATTADIA	DATE: 10MAR2008
DRAWN BY: FAROLE		CHECKED BY: FAROLE	DATE: 10MAR2008
DIMENSIONS: INCHES		APPROVED BY: FAROLE	DATE: 10MAR2008
NO DIMENSIONS SPECIFIED: INCHES		NAME: D. FAROLE	DATE: 10MAR2008
0 P.L.C. ± .010		PRODUCT SPEC: 1X6 MA045(TM), MODULAR JACK, 70N2ETP1	
1 P.L.C. ± .010		APPLICATION SPEC: 108-2100	
2 P.L.C. ± .008		SIZE: A1	DATE: 00779
3 P.L.C. ± .008		DRAWING NO: C-6610168	
4 P.L.C. ± .008		RESTRICTED TO: CUSTOMER DRAWING	
ANGLES: ± .5		SCALE: NTS	
FINISH: NTS		SHEET: 1	REV: 2

7Q15ETP1 MAGNETIC CIRCUIT



Suggested PCB Layout
(Component Side)

C1 = 1000 pF, 2kV DECOUPLING CAPACITOR

R1 - R4 = 75 OHMS, 1/16W, 5% RESISTORS

C2 & C3 = 15 nF, 100 VDC CAPACITORS

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRW: S. ATTADIA - 10MAR2020		TE Connectivity
REVISED BY: D. FAROLE - 10MAR2020		CHK: D. FAROLE - 10MAR2020		
DIMENSIONS: INCHES		APD: D. FAROLE - 10MAR2020	NAME: 1X6 MA045(TM), MODULAR JACK, 7Q15ETP1	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC: 108-2100	V _{OH} /POE SCHEMATIC, 15ETP1 SERIES CIRCUIT,	
0.100	± .010	APPLICATION SPEC: -	SHIELDED, DECOUPLING CAPACITOR, WITH LEADS	
0.250	± .005	SIZE: -	DRAWING NO: A1 00779 C=6610168	
0.500	± .002	SCALE: NTS	SHEET 2 OF 2	
MATERIAL: -	FINISH: -	WEIGHT: -	REV D	
CUSTOMER DRAWING		RESTRICTED TO:		